Company Contact: Justin Moll , Pixus Technologies Justin.moll@pixustechnologies.com 519-885-5775

Pixus Offers Range of Ventilated Panels for Instrumentation Cases

Waterloo, Ontario — Apr 06, 2018 – Pixus Technologies, a provider of embedded computing and enclosure solutions, has several sizes for its ventilated panels for electronics enclosures. The panels fit the company's modular Rittal Vario™ and RiCase™ aluminum cases.

The ventilation panels allow airflow in Pixus' instrumentation cases. Customers can mix-and-match ventilated and non-ventilated panels on the front or rear of the enclosure. The panels come in 84HP and 42HP size for 19" and 9.5" enclosures respectively. Hinged panels are also available. Panel customization is optional, including custom cut-outs, painting/powder coating, and silkscreening.

Pixus provides instrumentation cases in 1U-12U heights and various widths, depths. The company also offers open standard backplane and chassis platforms as well as related embedded computing components.

About Pixus Technologies

Leveraging over 25 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on OpenVPX, MicroTCA, ATCA, cPCI Serial, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.